

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Add device types 02 through 06. Add vendor CAGE 64155. Change CAGE code to 67268.	88-06-28	M. A. FRYE
B	Add case outline letter 2. Changes in accordance with N.O.R. 5962-R104-94.	94-02-24	M. A. FRYE
C	Add case outline Y. Make changes to 1.2.2, 1.3, 3.2.1, figure 1, and figure 2. Redrawn. - ro	99-10-14	R. MONNIN
D	Drawing updated to reflect current requirements. - ro	02-07-24	R. MONNIN
E	Add device class V devices and add TABLE IIB. - ro	02-12-06	R. MONNIN
F	Drawing updated as part of 5 year review. -rrp	09-12-14	C. SAFFLE
G	Add device type 61. Add radiation assurance requirements. - ro	14-02-04	C. SAFFLE
H	Drawing updated to reflect current MIL-PRF-38535 requirements. -rrp	20-06-16	J. ESCHMEYER



CURRENT CAGE CODE 67268

THE ORIGINAL FIRST PAGE OF THIS DRAWING HAS BEEN REPLACED.

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REV STATUS	REV	H	H	H	H	H	H	H	H	H	H	H	H	H	H	H	
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13			

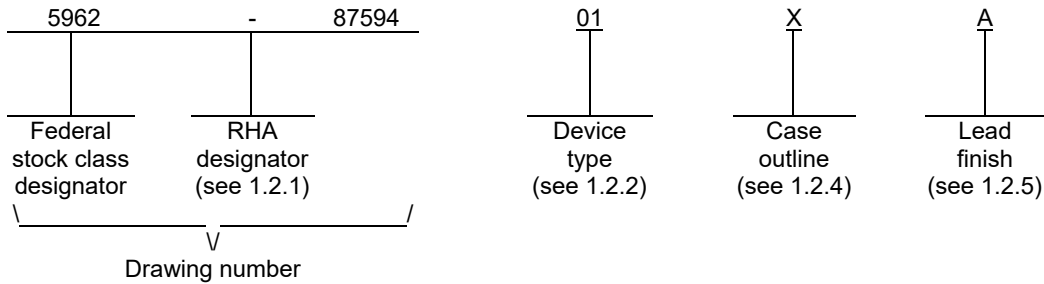
PMIC N/A	PREPARED BY Charles E. Besore	<p align="center">DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 https://www.dla.mil/LandandMaritime</p>																	
<p align="center">STANDARD MICROCIRCUIT DRAWING</p> <p>THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p> <p align="center">AMSC N/A</p>	CHECKED BY D. A. DiCenzo																		
	APPROVED BY Nelson Hauck	<p align="center">MICROCIRCUIT, LINEAR, VOLTAGE REFERENCE, MONOLITHIC SILICON</p>																	
	DRAWING APPROVAL DATE 87-05-29																		
	REVISION LEVEL H	<table border="1"> <tr> <td>SIZE A</td> <td>CAGE CODE 14933</td> <td>5962-87594</td> </tr> <tr> <td colspan="3">SHEET 1 OF 13</td> </tr> </table>	SIZE A	CAGE CODE 14933	5962-87594	SHEET 1 OF 13													
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1. SCOPE

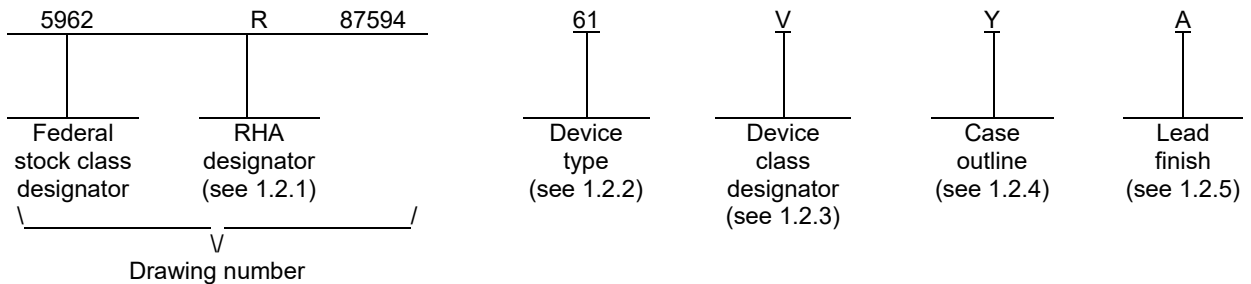
1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device class Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 PIN. The PIN is as shown in the following examples.

For device class M and Q:



For device class V:



1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	LM185-1.2	Voltage reference diode
02	LM185-2.5	Voltage reference diode
03	LM185BX1.2	Voltage reference diode
04	LM185BX2.5	Voltage reference diode
05	LM185BY1.2	Voltage reference diode
06	LM185BY2.5	Voltage reference diode
61	LM185H-1.2	Voltage reference diode

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1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as listed below. Since the device class designator has been added after the original issuance of this drawing, device classes M and Q designators will not be included in the PIN and will not be marked on the device.

<u>Device class</u>	<u>Device requirements documentation</u>
M	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
X	See figure 1	2	TO-46 can
Y	GDFP1-G10	10	Flat pack with gullwing leads
2	CQCC1-N20	20	Square leadless chip carrier

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

1.3 Absolute maximum ratings. ^{1/}

Reverse current (IR)	30 mA
Forward current (IF)	10 mA
Maximum power dissipation (PD)	113 mW
Junction temperature (T _J)	+175°C
Lead temperature (soldering 10 seconds):	
Cases X and 2	+300°C
Case Y	+260°C
Storage temperature range	-55°C to +150°C
Thermal resistance, junction-to-case (θ _{JC}):	
Case X	80°C/W
Case Y	23°C/W
Case 2	See MIL-STD-1835
Thermal resistance, junction-to-ambient (θ _{JA}):	
Case X	440°C/W
Case Y	194°C/W
Case 2	100°C/W

1.4 Recommended operating conditions.

Ambient operating temperature range (T _A)	-55°C to +125°C
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^{1/} Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

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1.5 Radiation features.

Maximum total dose available (dose rate = 0.010 rads(Si)/s) 100 krads(Si) 2/

The manufacturer supplying RHA parts on this drawing has performed a characterization test to demonstrate if the parts exhibit enhanced low dose rate sensitivity (ELDRS) according to MIL-STD-883 method 1019 paragraph 3.13.1.1. These parts have been characterized and observed to be enhanced low dose rate sensitive. However, the characterization test demonstrated the parts did pass the radiation end point parameter limits under low dose rate conditions according to MIL-STD-883 method 1019 paragraph 3.13.3.b. The manufacturer will continue to perform low dose rate lot acceptance testing on each wafer lot or wafer according to method 1019 of MIL-STD-883.

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <https://quicksearch.dla.mil>.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

2/ For device type 61, these part have been tested and exhibit enhanced low dose rate sensitivity (ELDRS) effects. Radiation end point limits for the noted parameters are guaranteed for the conditions specified in MIL-STD-883, method 1019, condition D and paragraph 3.13.3.b.

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3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein and figure 1 .

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Radiation exposure circuit. The radiation exposure circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing and acquiring activity upon request.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table IA and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table IA.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DLA Land and Maritime-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 Verification and review for device class M. For device class M, DLA Land and Maritime, DLA Land and Maritime 's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 59 (see MIL-PRF-38535, appendix A).

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TABLE IA. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/ 2/</u> -55°C ≤ TA ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Reverse breakdown voltage	VREF	IR = 10 μA	1	01,03, 05,61	1.223	1.247	V
		10 μA ≤ IR ≤ 20 μA	2,3		1.205	1.26	
		IR = 20 μA	1	02,04, 06	2.462	2.538	V
		20 μA ≤ IR ≤ 30 μA	2,3		2.425	2.575	
		IR = 1 mA	1	01,03, 05,61	1.223	1.247	V
					2,3	1.205	
			02,04, 06	1	2.462	2.538	V
				2,3	2.425	2.575	
		IR = 20 mA	1	01,03, 05,61	1.223	1.247	V
					2,3	1.205	
			02,04, 06	1	2.462	2.538	V
				2,3	2.425	2.575	
Reverse breakdown voltage change with current	ΔVREF /	10 μA ≤ IR ≤ 1 mA	1	01,03, 05,61	-1	1	mV
		20 μA ≤ IR ≤ 1 mA	2,3		-1.5	1.5	
	ΔIR	20 μA ≤ IR ≤ 1 mA	1	02,04, 06	-1	1	mV
		30 μA ≤ IR ≤ 1 mA	2,3		-1.5	1.5	
		1 mA ≤ IR ≤ 20 mA	1	All	-10	10	mV
2,3	-20	20					
Forward bias voltage	VF	IF = 2 mA, TA = +25°C	1	All	-1	-0.4	V

See footnotes at end of table.

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TABLE IA. Electrical performance characteristics – Continued.

Test	Symbol	Conditions <u>1/ 2/</u> -55°C ≤ TA ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Temperature coefficient <u>3/</u>	TC		1,2,3	03, 04		30	ppm/°C
				05, 06		50	

- 1/ Device type 61 supplied to this drawing are characterized and tested through all levels M, D, P, L, and R of irradiation. Pre and Post irradiation values are identical unless otherwise specified in Table IB. When performing post irradiation electrical measurements for any RHA level, TA = +25°C.
- 2/ Device type 61 has been tested and exhibit enhanced low dose rate sensitivity (ELDRS) effects. Radiation end point limits for the noted parameters are guaranteed for the conditions specified in MIL-STD-883, method 1019, condition D and paragraph 3.13.3.b with an overtest factor of 1.5X. For 100 krad, units are tested to 150 krad and still meet the radiation end point limits.
- 3/ The average temperature coefficient is defined as the maximum deviation of reference voltage at all measured temperatures between the operating TMAX and TMIN divided by TMAX – TMIN. The measured temperatures are -55°C, -40°C, 0°C, +25°C, +70°C, +85°C, and +125°C.

TABLE IB. Post irradiation (low dose rate) reference voltage drift limits.

Test	Symbol	Conditions Device type 61	RHA level designators	Group A subgroups	Post radiation at 25°C drift limit	
					Min	Max
Reverse breakdown voltage tolerance	VREF	IR = 10 μA	R	1	-3%	+3%
		IR = 1 mA	R		-3%	+3%
		IR = 15 mA	R		-2.5%	+2.5%
Reverse breakdown voltage change with current	ΔVREF/	10 μA < IR < 1 mA	R	1	-15 mV	15 mV
	ΔIR	1 mA < IR < 20 mA	R		-25 mV	25 mV
Forward bias voltage	VF	IF = 2 mA	R	1	-1 V	-0.4 V

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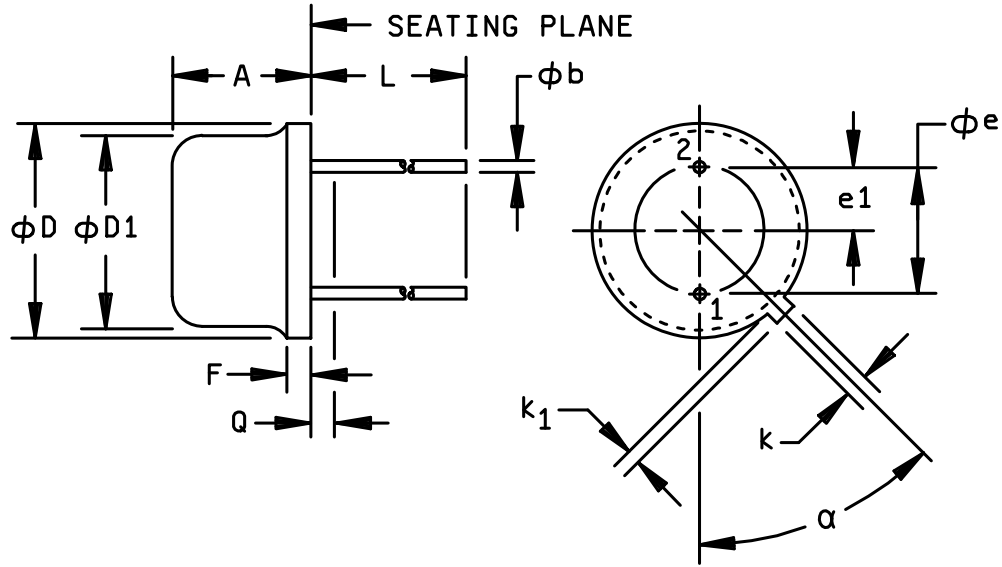
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Case X



Symbol	Inches		Millimeters	
	Min	Max	Min	Max
A	.080	.105	2.03	2.67
ϕb	.016	.019	0.41	0.48
ϕD	.209	.219	5.31	5.56
$\phi D1$.178	.195	4.52	4.95
ϕe	---	.100	---	2.54
e1	---	.050	---	1.27
F	---	.030	---	0.76
k	.036	.046	0.91	1.17
k1	.028	.048	0.71	1.22
L	.500	---	12.70	---
Q	---	.025	---	0.64
α	45° BSC		45° BSC	

NOTES:

1. Dimensions are in inches.
2. Metric equivalents are given for general information only.
3. The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. Case outline.

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Device types	All		
Case outlines	X	Y	2
Terminal number	Terminal symbol		
1	VREF	NC	GND
2	GND	NC	NC
3	---	NC	NC
4	---	NC	NC
5	---	V-	NC
6	---	NC	NC
7	---	NC	NC
8	---	NC	NC
9	---	NC	NC
10	---	V+	NC
11	---	---	VREF+
12	---	---	NC
13	---	---	NC
14	---	---	NC
15	---	---	NC
16	---	---	NC
17	---	---	NC
18	---	---	NC
19	---	---	NC
20	---	---	NC

NC = No connection

FIGURE 2. Terminal connections.

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4. VERIFICATION

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015.
 - (2) TA = +125°C, minimum.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.

4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 4, 5, 6, 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

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TABLE IIA. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	----	----	----
Final electrical parameters (see 4.2)	1,2,3 <u>1/</u>	1,2,3 <u>1/</u>	1,2,3 <u>1/</u>
Group A test requirements (see 4.4)	1,2,3	1,2,3	1,2,3
Group C end-point electrical parameters (see 4.4)	1,2,3	1,2,3	1,2,3 <u>2/</u>
Group D end-point electrical parameters (see 4.4)	1,2,3	1,2,3	1,2,3
Group E end-point electrical parameters (see 4.4)	---	---	1

1/ PDA applies to subgroup 1.

2/ Delta limits as specified in table IIB shall be required where specified, and delta limits shall be computed with reference to the previous end point electrical parameters.

TABLE IIB. Delta limits at +25°C.

Test	Symbol	Conditions	Group A subgroup	Device type	Limits		Unit
					Min	Max	
Reverse breakdown voltage	VREF	IR = 10 μ A	1	01, 61	-0.01	0.01	V
		IR = 20 mA			-0.01	0.01	
		IR = 20 μ A	02	-10	10	mV	
		IR = 20 mA					

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4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b. $T_A = +125^{\circ}\text{C}$, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table IA at $T_A = +25^{\circ}\text{C} \pm 5^{\circ}\text{C}$, after exposure, to the subgroups specified in table IIA herein.

4.4.4.1 Total dose irradiation testing. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019, condition D for device type 61 and as specified herein.

4.4.4.1.1 Accelerated annealing test. Accelerated annealing tests shall be performed on all devices requiring a RHA level greater than 5 krad (Si). The post-anneal end-point electrical parameter limits shall be as specified in table IA herein and shall be the pre-irradiation end-point electrical parameter limit at $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$. Testing shall be performed at initial qualification and after any design or process changes which may affect the RHA response of the device.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

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6.3 Record of users. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.

6.4 Comments. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in MIL-HDBK-103 and QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

6.6.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-87594
		REVISION LEVEL H	SHEET 13

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 20-06-16

Approved sources of supply for SMD 5962-87594 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <https://landandmaritimeapps.dla.mil/programs/smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-8759401XA	01295	LM185H-1.2/883
	<u>3/</u>	LM185H-1.2/883
5962-8759401YA	01295	LM185WG-1.2/883
5962-87594012A	<u>3/</u>	LM185E1.2/883
5962-8759402XA	01295	LM185H-2.5/883
	<u>3/</u>	LM185H-2.5/883
5962-8759402YA	01295	LM185WG-2.5/883
5962-87594022A	<u>3/</u>	LM185E2.5/883
5962-8759403XA	<u>3/</u>	LM185BXH1.2/883
5962-8759404XA	<u>3/</u>	LM185BXH2.5/883
5962-8759405XA	01295	LM185BYH1.2/883
5962-8759406XA	<u>3/</u>	LM185BYH2.5/883
5962-8759401VXA	<u>3/</u>	LM185H-1.2-QV
5962-8759401VYA	<u>3/</u>	LM185WG-1.2-QV
5962-8759402VYA	<u>3/</u>	LM185WG-2.5-QV
5962-8759406VXA	01295	LM185BYH2.5-QV
5962R8759461VXA	01295	LM185H-1.2RLQV
5962R8759461VYA	01295	LM185WG-1.2RLQV

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGE
number

01295

Vendor name
and address

Texas Instruments, Inc.
Semiconductor Group
8505 Forest Ln.
PO Box 660199
Dallas, TX 75243

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.